

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	119	257/E23.067	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/09/25 15:32
L2	132	257/E23.068	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/09/25 15:32
L3	3339	257/48	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/09/25 15:34
L4	6102	257/666	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/09/25 15:39
L5	2147	349/117	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/09/25 15:59
L6	6204	428/403	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/09/25 16:15
L7	1236	75/255	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/09/25 16:30

L8	374	362/458	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/09/25 16:37
L9	17	(semiconductor or die or dice or chip or lc) and (copper or "Cu") with (bump or pad or electrode) and (copper or "Cu") with "10" near (microns or micrometer or "mu. m") and solder with "40" near (microns or micrometer or "mu. m")	USPAT	OR	OFF	2009/09/25 17:13
L10	4883	362/800	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/09/25 17:59
L11	3804	439/66	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/09/25 18:10
L12	1396	439/91	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/09/25 18:37
L13	8806	324/765	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/09/25 19:06
L14	2216	324/761	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/09/25 19:20

L15	6821	324/754	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/09/25 19:44
L16	1413	324/757	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/09/25 20:20
S1	1	"20070040245"	US-PGPUB; USPAT	OR	OFF	2009/09/22 21:51
S2	49	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) with (via or open\$3 or hole) and elastic near polymer	USPAT	OR	ON	2009/09/23 19:18
S3	385	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) with (via or open\$3 or hole) and elastic near (polymer or layer or film)	USPAT	OR	ON	2009/09/23 19:24
S4	336	S3 not S2	USPAT	OR	ON	2009/09/23 19:25
S5	3880	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or elastic) with (via or open\$3 or hole) and elastic with (polymer or layer or film or insulat\$3 or dielectric)	USPAT	OR	ON	2009/09/23 19:54
S6	212	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or elastic) with (via or open\$3 or hole) and elastic with (polymer or layer or film or insulat\$3 or dielectric) and anisotropica\$3	USPAT	OR	ON	2009/09/23 19:54

S7	212	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or elastic or elastomer) with (via or open\$3 or hole) and elastic with (polymer or layer or film or insulat\$3 or dielectric) and anisotropica\$3	USPAT	OR	ON	2009/09/23 19:55
S8	6880	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or elastic or elastomer) with (via or open\$3 or hole) and anisotropica\$3	USPAT	OR	ON	2009/09/23 19:55
S9	1412	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or elastic or elastomer) with (via or open\$3 or hole) and anisotropica\$3 near (sheet or layer or film)	USPAT	OR	ON	2009/09/23 19:55
S10	0	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or elastic or elastomer) with (via or open\$3 or hole) and anisotropica\$3 near (sheet or layer or film) and big\$3 near (open \$3 or diameter)	USPAT	OR	ON	2009/09/23 20:02
S11	0	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or elastic or elastomer) with (via or open\$3 or hole) and anisotropica\$3 near (sheet or layer or film) and (big\$3 or lager) with (open\$3 or diameter)	USPAT	OR	ON	2009/09/23 20:03

S12	0	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or elastic or elastomer) with (via or open\$3 or hole) and anisotropica\$3 near (sheet or layer or film) and (big or bigger or lager) with (open\$3 or diameter)	USPAT	OR	ON	2009/09/23 20:03
S13	0	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or elastic or elastomer) with (via or open\$3 or hole) and anisotropica\$3 near (sheet or layer or film) and (big or bigger or lager) with (open\$3 or hole or via) near (surface or side or diameter)	USPAT	OR	ON	2009/09/23 20:04
S14	1412	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or elastic or elastomer) with (via or open\$3 or hole) and anisotropica\$3 near (sheet or layer or film)	USPAT	OR	ON	2009/09/23 20:04
S15	17	(semiconductor or die or dice or chip or Ic) and ( elastic or elastomer) with (via or open\$3 or hole) and anisotropica\$3 near (sheet or layer or film)	USPAT	OR	ON	2009/09/23 20:29
S16	62	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) with (elastic or elastomer) and (via or open\$3 or hole) with anisotropica\$3	USPAT	OR	ON	2009/09/23 20:30
S17	1	"5622896".pn.	USPAT	OR	ON	2009/09/23 20:36
S18	1	"5622896".pn. and solvent with ketone	USPAT	OR	ON	2009/09/23 20:37

S19	4	("20050146336"   "6297652"   "6720787").PN. OR ("7038471").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/09/23 20:43
S20	8	("5903162"   "5973505"   "6133744"   "6540527").PN. OR ("6906541").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/09/23 20:45
S21	151	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) with (elastic or elastomer) and (via or open\$3 or hole) with anisotropic\$4	USPAT	OR	ON	2009/09/23 20:51
S22	89	S21 not S16	USPAT	OR	ON	2009/09/23 20:51
S23	2	"20020191406"	US-PGPUB; USPAT	OR	ON	2009/09/23 20:54
S24	105	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) with (made or form\$2) with (elastic or elastomer) and (via or open\$3 or hole) with anisotropic \$4	USPAT	OR	ON	2009/09/23 21:05
S25	584	(semiconductor or die or dice or chip or Ic) and flexible with (base or film or layer) and (via or open\$3 or hole) with anisotropic\$4	USPAT	OR	ON	2009/09/23 21:07
S26	541	S25 not S21	USPAT	OR	ON	2009/09/23 21:07
S27	12	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) with (elastic or elastomer) and (via or open\$3 or hole) with (conduct\$3 near paste) and anisotropic \$4	USPAT	OR	ON	2009/09/23 21:45

S28	48	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) with (elastic or elastomer) and (via or open\$3 or hole) with (conduct\$3 near (paste or particles)) and anisotropic\$4	USPAT	OR	ON	2009/09/23 21:46
S29	48	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) with (elastic or elastomer) and (via or open\$3 or hole) with (conduct\$3 near (paste or particles or powder)) and anisotropic\$4	USPAT	OR	ON	2009/09/23 21:46
S30	120	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) with (elastic or elastomer or flexible) and (via or open\$3 or hole) with (conduct\$3 near (paste or particles or powder)) and anisotropic\$4	USPAT	OR	ON	2009/09/23 21:49
S31	72	S30 not S29	USPAT	OR	ON	2009/09/23 21:49
S32	62	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) with (elastic or elastomer) and (via or open\$3 or hole) with ((conduct\$3 or metal\$3) with (paste or particles or powder)) and anisotropic\$4	USPAT	OR	ON	2009/09/23 21:52

S33	76	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or base) with (elastic or elastomer) and (via or open\$3 or hole) with ((conduct\$3 or metal\$3) with (paste or particles or powder)) and anisotropic\$4	USPAT	OR	ON	2009/09/23 21:57
S34	14	S33 not S32	USPAT	OR	ON	2009/09/23 21:58
S35	6	("20040091687"   "6359235"   "6512182"   "6680441"   "6928726"   "7022399").PN. OR ("7287321").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/09/23 22:00
S36	215	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or base) with (elastic or elastomer) and (via or open\$3 or hole) with ((conduct\$3 or metal\$3) with (paste or particles or powder))	USPAT	OR	ON	2009/09/23 22:05
S37	171	S36 not S21	USPAT	OR	ON	2009/09/23 22:05
S38	125	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or base or substrate or layer or film) with (elastic or elastomer) and (via or open\$3 or hole) with ((conduct\$3 or metal \$3) with (paste or particles or powder)) and anisotropi\$4	USPAT	OR	ON	2009/09/24 14:13
S39	14	("5140405"   "5162613"   "5975915").PN. OR ("6690564").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/09/24 14:35
S40	1	"20020061401"	US-PGPUB; USPAT; USOCR	OR	OFF	2009/09/24 14:38



S41	1	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or base or substrate or layer or film) with (elastic or elastomer) and (via or open\$3 or hole) with ((conduct\$3 or metal \$3) with (paste or particles or powder)) and anisotropi\$4 and "20020061401"	US-PGPUB	OR	ON	2009/09/24 14:39
S45	12	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or base or substrate or layer or film) with (silicon near rubber) and (via or open\$3 or hole) with ((conduct\$3 or metal \$3) with (paste or particles or powder)) and anisotropi\$4	US-PGPUB	OR	ON	2009/09/24 17:28
S46	19	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or base or substrate or layer or film) with (silicon near rubber) and (via or open\$3 or hole) with ((conduct\$3 or metal \$3) with (paste or particles or powder)) and anisotropi\$4	US-PGPUB; USPAT	OR	ON	2009/09/24 17:28
S47	0	(semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) and (via or open\$3 or hole) with ((conduct\$3 or metal \$3) with (paste or particles or powder)) and anisotropi\$4 and (via or open\$3 or hole) with slop	USPAT	OR	ON	2009/09/24 18:37

S48	3	(semiconductor or die or dice or chip or IC) and (insulator or dielectric) and (via or open or hole) with ((conductor or metal) with (paste or particles or powder)) and anisotropic and (via or open or hole) with (big or bigger or larger) near (surface or side)	USPAT	OR	ON	2009/09/24 18:38
S49	1	"20020071077"	US-PGPUB; USPAT	OR	ON	2009/09/24 19:13
S50	6	stack near (semiconductor or die or dice or IC or chip) and (middle or center) near (semiconductor or die or dice or IC or chip) with (across) with (pattern or metal or circuit)	USPAT	OR	ON	2009/09/25 13:25
S51	57	stack near (semiconductor or die or dice or IC or chip) and (middle or center) near (semiconductor or die or dice or IC or chip) with (pattern or metal or circuit)	USPAT	OR	ON	2009/09/25 13:26
S52	46	stack near (semiconductor or die or dice or IC or chip) and relay with (pads or finger or pattern or circuit)	USPAT	OR	ON	2009/09/25 13:28
S54	11	("5012323"   "5347159"   "5347428"   "5422435"   "5495398"   "5767570"   "5903049"   "5905639"   "5976911"   "6133637").PN. OR ("6958532").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/09/25 13:37

S55	0	stack\$3 near (semiconductor or die or dice or IC or chip) and across\$3 with (pads or finger or pattern or circuit)	USPAT	OR	ON	2009/09/25 13:48
S56	649	stack\$3 near (semiconductor or die or dice or IC or chip) and across\$3 with (pads or finger or pattern or circuit)	USPAT	OR	ON	2009/09/25 13:48
S57	1	stack\$3 near (semiconductor or die or dice or IC or chip) and across\$3 with (pads or finger or pattern or circuit) and relay\$3 with wir\$3	USPAT	OR	ON	2009/09/25 13:49
S58	10	stack\$3 near (semiconductor or die or dice or IC or chip) and cross\$3 with (pads or finger or pattern or circuit) and relay\$3 with wir\$3	USPAT	OR	ON	2009/09/25 13:49
S59	3	("6037661"   "6410987").PN. OR ("6798071").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/09/25 13:52
S60	46	("5422435"   "6005778").PN. OR ("6215182").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/09/25 13:52
S61	14	stack\$3 near (semiconductor or die or dice or IC or chip) and edge with (pads or finger or pattern or circuit) and relay\$3 with wir\$3	USPAT	OR	ON	2009/09/25 13:54
S62	461	stack\$3 near (semiconductor or die or dice or IC or chip) and across\$3 with (pads or finger or pattern or circuit) and wir\$3	USPAT	OR	ON	2009/09/25 13:54

S63	142	stack\$3 near (semiconductor or die or dice or IC or chip) and linear with (pads or finger or pattern or circuit) and wir\$3	USPAT	OR	ON	2009/09/25 13:58
S64	35	("20030038378"   "4341594"   "4803147"   "4948754"   "5049980"   "5323060"   "5366906"   "5384488"   "5506756"   "5554887"   "5672912"   "5677576"   "5683942"   "5814894"   "5834844"   "5844304"   "5851911"   "5886415"   "5925931"   "5971253"   "5977641"   "6043109"   "6072236"   "6117539"   "6181569"   "6212767"   "6228687"   "6255737"   "6294407"   "6376904"   "6534853"   "6573609"   "6590292").PN. OR ("6987325").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/09/25 14:03
S65	2667	stack\$3 near (semiconductor or die or dice or IC or chip) and (redistribut\$3 or redirect\$3 or rerout\$3 or interposer or interconnect\$3) with (semiconductor or die or dice or IC or chip)	USPAT	OR	ON	2009/09/25 14:05

S66	2090	stack\$3 near (semiconductor or die or dice or IC or chip) and (redistribut\$3 or redirect\$3 or rerout\$3 or interposer or interconnect\$3) with (semiconductor or die or dice or IC or chip) and wir\$3	USPAT	OR	ON	2009/09/25 14:05
S67	460	stack\$3 near (semiconductor or die or dice or IC or chip) and (redistribut\$3 or redirect\$3 or rerout\$3 or interposer or interconnect\$3) with (semiconductor or die or dice or IC or chip) and wir\$3 and (cross \$3 or across\$3) with (redistribut\$3 or redirect\$3 or rerout\$3 or interposer or interconnect\$3)	USPAT	OR	ON	2009/09/25 14:06
S68	14	("20050172894"   "20060267173"   "5012323"   "5206188"   "5285104"   "5299097"   "5495398"   "6376904"   "6441495"   "6472758"   "6514794"   "6621155"   "6843421"   "6900528").PN. OR ("7592691").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/09/25 14:07

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